

IN THE CLAIMS:

Claims 1 through 7 have been amended herein. All of the pending claims 1 through 7 are presented below. This listing of claims will replace all prior versions and listings of claims in the application. Please enter these claims as amended.

Listing of Claims:

1. (Currently amended) A method of forming a semiconductor device assembly, said method comprising:
providing a substrate having an upper surface and a lower surface;
depositing a layer of copper on ~~one surface of~~ the upper surface and the lower surface of the substrate;
patterning the layer of copper on the one surface of the upper surface and the lower surface of the substrate to form at least one bond pad thereon;
depositing at least one layer of metal on at least a portion of the layer of copper; and
connecting one end of a ~~conductor~~ conductive lead of a TAB tape to the at least one layer of metal.

2. (Currently amended) The method of claim 1, further comprising:
connecting one end of the ~~conductor~~ conductive lead of the TAB tape to the at least one layer of metal using a wire bond.

3. (Currently amended) A method of forming a semiconductor device assembly, said method comprising:
providing a substrate having an upper surface and a lower surface;
depositing a layer of copper on the ~~one surface of~~ the upper surface and the lower surface of the substrate;

patterning the layer of copper on one surface of the upper surface and the lower surface of the substrate to form at least one bond pad thereon;
depositing at least one layer of gold metal on at least a portion of the layer of copper; and
connecting one end of a ~~conductor~~ conductive lead of a TAB tape to the at least one layer of gold metal.

4. (Currently amended) A method of forming a semiconductor device assembly having a substrate having an upper surface and a lower surface, said method comprising:
depositing a layer of copper on ~~one surface of~~ the upper surface and the lower surface of the substrate;
patterning the layer of copper on the one surface of the upper surface and the lower surface of the substrate to form at least one bond pad thereon;
depositing at least one layer of metal on at least a portion of the layer of copper; and
connecting one end of a ~~conductor~~ conductive lead of a TAB tape to the at least one layer of metal.

5. (Currently amended) The method of claim 4, further comprising:
connecting one end of the ~~conductor~~ conductive lead of the TAB tape to the at least one layer of metal using a wire bond.

6. (Currently amended) A method of forming a semiconductor device assembly having a substrate having an upper surface and a lower surface, said method comprising:
depositing a layer of copper on one surface of the upper surface and the lower surface of the substrate;
patterning the layer of copper on ~~the one surface of~~ the upper surface and the lower surface of the substrate to form at least one bond pad thereon;
depositing at least one layer of gold metal on at least a portion of the layer of copper; and

connecting one end of a ~~conductor~~ conductive lead of a TAB tape to the at least one layer of gold metal.

7. (Currently amended) A method of forming a semiconductor device assembly having a substrate having an upper surface and a lower surface, said method comprising:
depositing a layer of copper on one surface of the upper surface and the lower surface of the substrate;
patterning the layer of copper on the one surface of the upper surface and the lower surface of the substrate to form at least one bond pad thereon;
depositing at least one layer of gold metal on at least a portion of the layer of copper; and
connecting one of an end of a ~~conductor~~ conductive lead of a TAB tape and a portion of a bond wire to the at least one layer of gold metal.